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#### Contract

# **UKRI-3154 Indium deposition system**

**UK Research & Innovation** 

F03: Contract award notice

Notice identifier: 2024/S 000-000402

Procurement identifier (OCID): ocds-h6vhtk-040425

Published 5 January 2024, 4:06pm

## **Section I: Contracting authority**

### I.1) Name and addresses

**UK Research & Innovation** 

https://www.ukri.org, North Star Avenue, Harwell

Swindon

SN21FL

#### Contact

Declan Ward

#### **Email**

commercial@ukri.org

#### **Telephone**

+44 1793442000

## Country

United Kingdom

## Region code

UKK14 - Swindon

## Internet address(es)

Main address

https://www.ukri.org

# I.4) Type of the contracting authority

Body governed by public law

# I.5) Main activity

Other activity

Research and innovation

# **Section II: Object**

### II.1) Scope of the procurement

#### II.1.1) Title

UKRI-3154 Indium deposition system

Reference number

**UKRI-3154** 

#### II.1.2) Main CPV code

• 14763000 - Indium

#### II.1.3) Type of contract

**Supplies** 

#### II.1.4) Short description

STFC Interconnect provides a range of electronic and detector assembly techniques to scientific communities within STFC and our external collaborations. We have developed a process to perform surface preparation and make micro bumps of pure Indium metal, on a range of substrates including semiconductor wafers and semiconductor die. The resulting bumps are then used in our proprietary flip chip process to make many thousands or tens-of-thousands of electrical/mechanical connections in a single bonding step. The deposition process involves masking prior to deposition, then deposition, followed by removal of masked areas, leaving the desired bumps in place. Photo lithography (negative resist, lift-off) and shadow masking techniques are both used. We are now scaling this process into production and need new equipment capable of depositing on multiple substrates per day.

### II.1.6) Information about lots

This contract is divided into lots: No

## II.1.7) Total value of the procurement (excluding VAT)

Value excluding VAT: £185,067

### II.2) Description

#### II.2.3) Place of performance

**NUTS** codes

• UKJ14 - Oxfordshire

Main site or place of performance

Oxfordshire

#### II.2.4) Description of the procurement

STFC Interconnect provides a range of electronic and detector assembly techniques to scientific communities within STFC and our external collaborations. We have developed a process to perform surface preparation and make micro bumps of pure Indium metal, on a range of substrates including semiconductor wafers and semiconductor die. The resulting bumps are then used in our proprietary flip chip process to make many thousands or tens-of-thousands of electrical/mechanical connections in a single bonding step. The deposition process involves masking prior to deposition, then deposition, followed by removal of masked areas, leaving the desired bumps in place. Photo lithography (negative resist, lift-off) and shadow masking techniques are both used. We are now scaling this process into production and need new equipment capable of depositing on multiple substrates per day.

### II.2.5) Award criteria

Quality criterion - Name: Quality / Weighting: 70

Cost criterion - Name: Price / Weighting: 30

#### II.2.11) Information about options

Options: No

### II.2.13) Information about European Union Funds

The procurement is related to a project and/or programme financed by European Union funds: No

# Section IV. Procedure

## IV.1) Description

## IV.1.1) Type of procedure

Open procedure

#### IV.1.8) Information about the Government Procurement Agreement (GPA)

The procurement is covered by the Government Procurement Agreement: Yes

## IV.2) Administrative information

#### IV.2.1) Previous publication concerning this procedure

Notice number: <u>2023/S 000-028493</u>

## Section V. Award of contract

#### **Contract No**

**UKRI-3154** 

#### **Title**

Indium deposition system

A contract/lot is awarded: Yes

## V.2) Award of contract

## V.2.1) Date of conclusion of the contract

20 December 2023

### V.2.2) Information about tenders

Number of tenders received: 3

The contract has been awarded to a group of economic operators: No

#### V.2.3) Name and address of the contractor

HHV Ltd

Unit 14 Lloyds Court

Crawley

**RH10 9QX** 

Country

**United Kingdom** 

**NUTS** code

• UKJ14 - Oxfordshire

National registration number

06738557

The contractor is an SME

Yes

### V.2.4) Information on value of contract/lot (excluding VAT)

Initial estimated total value of the contract/lot: £185,067

Total value of the contract/lot: £185,067

## **Section VI. Complementary information**

## VI.3) Additional information

The contracting authority considers that this contract may be suitable for economic operators that are small or medium enterprises (SMEs). However, any selection of tenderers will be based solely on the criteria set out for the procurement. Procurement Contract Transparency Data: Redacted contract documents will be made available within the next 30 days on the UKRI website at: <a href="https://www.ukri.org/about-us/procurement-contract-transparency-data/">https://www.ukri.org/about-us/procurement-contract-transparency-data/</a>

To view this notice, please click here:

https://ukri.delta-esourcing.com/delta/viewNotice.html?noticeId=833356262

GO Reference: GO-202415-PRO-24908448

## VI.4) Procedures for review

### VI.4.1) Review body

**UK Research and Innovation** 

Polaris House,, North Star Avenue

Swindon

SN21FL

**Email** 

commercial@ukri.org

Country

**United Kingdom** 

## VI.4.2) Body responsible for mediation procedures

**UK Research and Innovation** 

Polaris House,, North Star Avenue

Swindon

SN21FL

Email

commercial@ukri.org

Country

**United Kingdom**